Material Declaration Report

Part Number:	PI2EQX3211BHE
Package Type:	SSOP 20L
Pericom Package Code:	H20 (Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A
Date of RoHS Compliant:	Apr 15, 2007'

Component Weight (mg):	165.800
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 160C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Date:	3/4/2008

Homogeneous Material Declaration

ITEM	MATERIAL WEIGHT(mg)		MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	109.611	Supplier 1	Silica Fused	60676-86-0	90.800	99.5264
			Epoxy Resin 1	Proprietary	3.000	3.2883
			Epoxy Resin 2	Proprietary	2.000	2.1922
			Phenolic Resin	Proprietary	3.000	3.2883
			Aromatic Phosphate	Proprietary	1.000	1.0961
			Carbon Black	1333-86-4	0.200	0.2192
		Supplier 2	Silica Fused	60676-86-0	88.000	96.4573
			Epoxy Resin	Proprietary	5.000	5.4805
			Epoxy, Cresol Novolac	29690-82-2	2.000	2.1922
			Phenolic Resin	Proprietary	4.500	4.9325
			Carbon Black	1333-86-4	0.500	0.5481
LEADFRAME	44.336		Copper (Cu)	7440-50-8	96.440	42.7574
			Iron (Fe)	7439-89-6	2.350	1.0419
			Phosphorus (P)	7723-14-0	0.080	0.0355
			Zinc (Zn)	7440-66-6	0.130	0.0576
			Silver(Ag)	7440-22-4	1.000	0.4434
SILICON DIE	1.925		Silicon (Si)	7440-21-3	99.192	1.9092
			Non-hazardous Metal	Proprietary	0.808	0.0156
DIE ATTACH EPOXY	0.688	Supplier 1	Silver	7440-22-4	80.000	0.5505
			Epoxy Resin	Proprietary	17.000	0.1170
			Other non-hazardous substance	Proprietary	3.000	0.0206
		Supplier 2	Silver	7440-22-4	80.000	0.5505
			Epoxy Resin	Proprietary	5.000	0.0344
			Diester Resin	Proprietary	7.000	0.0482
			Functionalized Urethane	Proprietary	8.000	0.0550
GOLD WIRE	0.590		Gold(Au)	7440-57-43	99.990	0.5897
			Impurities	-	0.010	0.0001
SOLDER PLATING	8.651		Tin (Sn)	7440-31-5	99.990	8.6500
			Impurity	-	0.010	0.0009

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Device	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<19	<2	<2	<2	<5	<5
	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC

and

China RoHS Directive SJ/T11363-2006

Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium

Pb	Hg	Cr+6	Cd	PBB	PBDE
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm
O	O	O	O	O	O

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.